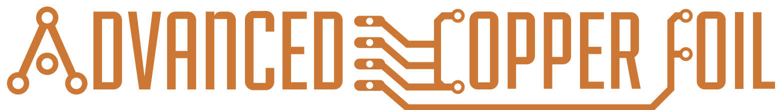


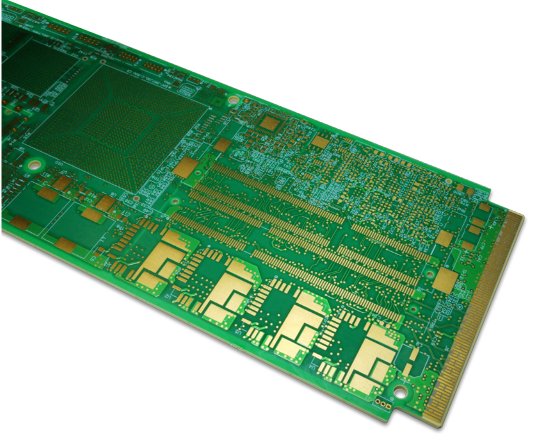
Distributed in the UK by

DATASHEET

Single-sided Poly Copper Protector with Carrier

Benefits

- Ease of handling copper foils compared to loose foils. This results in more efficient and quicker layup.
- 100% surface protection through lamination. No epoxy spots or other foreign materials possible with this system. No other product has 100% surface bonding.
- No need for costly 2 oz carrier on thin foils.



ACF-Screen is comprised of a Protective Poly release film adhered to a sheet of copper foil. It provides protection of the copper surface throughout the entire cycle of PCB lamination. ACF-Screen utilizes an inert adhesive which results in a residue-free copper surface during processing. The release film will uncouple during the lamination cycle, allowing for easy removal during break-down.

For example, we apply this release film to 9 µm copper foil to protect the surface and to allow for better handling during the layup process. There is no longer a need for expensive copper foil carriers.

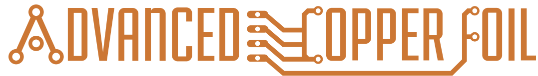
ACF Screen is available on 1/4 oz to 2 oz copper foils, including:

	Roughness (Rz)*
TW-YE Standard Shiny Foil with Zinc, HTE Grade 3	5 - 14 µm
TWS High Bond Foil with Zinc, HTE Grade 3	5 - 14 µm
TWLS Low Loss Foil with Zinc, HTE Grade 3	4 - 8 µm
BF-TZA Ultra Low Loss Foil, Zinc and Arsenic Free	< 2.5 µm

* Rz varies with copper thickness

Check the back for our full line of High Quality ED Copper Foils.

ACF



High Quality ED Copper Foil

	Product	Description	Application	Roughness (Rz)*
MATTE SIDE TREATED	TW-YE	Standard Shiny Foil with Zinc, HTE Grade 3	FR-4 Multi-layer	5 - 14 µm
	TWS	High Bond Foil with Zinc, HTE Grade 3	HTg, BT, Polyimide Multi-layer	5 - 14 µm
	TWLS	Low Loss Foil with Zinc, HTE Grade 3	High Speed, Low Loss Multi-layer and RF, Microwave Designs	4 - 8 µm
	BF-TZA	Ultra Low Loss Foil, Zinc and Arsenic Free	High Speed, Low Loss Multi-layer and RF, Digital Applications	< 2.5 µm
	TZA	Low Profile, Zinc and Arsenic Free	Halogen-free and Phenolic Cured Resin Systems	4 - 15 µm
	DTH-TW	Carrier Supported Foil, Double Thin	5 µm, 7 µm and 9 µm for Very Fine Line and HDI Circuit Boards	4.5 - 6.5 µm
	DTH-TZA	Carrier Supported Foil, Double Thin	2 µm, 3 µm and 5 µm for HDI Circuit Boards and IC Packaging	≤ 2.5 µm
	BF-TZA-FX	Flex Copper Foil, Low Profile, Zinc and Arsenic Free	Flexible Circuits	≤ 3.1 µm
	TZA-FX	Flex Copper Foil, Very Low Profile, Zinc and Arsenic Free	Flexible Circuits	4 - 12 µm
	BF-HFZ	Very Low Profile, Zinc Free	For the manufacture of PTFE Circuit Boards	2 - 3 µm
	BF-ANP	Almost No Profile	Our Flattest Copper Foils with Highest Data Transfer	1.3 - 1.6 µm
	BF-HFI-LP2	HVLP, Zinc Free	Inner Layer CCL Foil/Low Signal Loss, High Speed Digital	≤ 3.1 µm

	Product	Description	Application	Roughness (Rz)*
REVERSE SIDE TREATED	TZA-B	Low Profile, Zinc and Arsenic Free	Superior Oxidation Resistance for Halogen-free Resin Systems	5 - 9 µm
	TWS-B-YE	RTF High Bond Foil with Zinc	Inner Layer Foil/High Tg Laminates	5 - 15 µm
	HFZ-B	Low Profile, Zinc Free	Inner Layer Foil for PTFE Applications	6 - 10 µm

	Product	Description	Application	Roughness (Rz)*
RESIN COATED	BF-ANP-PA	Primer Coated Foil, Zinc and Arsenic Free	High Speed, Low Loss Multi-layer and RF, Digital Applications	≤ 1.2 µm

	Product	Description	Application	Roughness (Rz)*
NON TREATED	BF-Plainstain-proof	VLP Foil, Zinc and Arsenic Free	For Battery and Shielding Applications, No Treatment	1.2 - 2.5 µm

* Rz varies with copper thickness

For more info, visit our website at advancedcopperfoil.com

The information in this document is believed to be accurate, but Advanced Copper Foil makes no implied or expressed warranties to that accuracy and assumes no liability arising from its use. Users should conduct their own tests to determine the suitability of these products for their particular application. The listed data is within the normal range of product properties, but should not be the sole criteria for application design.

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